Chandler, Arizona, February 00, 2015 – Rogers Corporation (NYSE:ROG) unveiled its ULTRALAM® 3850HT liquid-crystal-polymer (LCP) laminates for simplified and improved construction of multilayer circuit boards at higher temperatures. With a melt temperature of +330°C, ULTRALAM 3850HT circuit materials are adhesiveless laminates that use LCP as the dielectric film to deliver high yields in single-layer and multilayer circuit constructions. These laminates are well suited for high-speed and high-frequency circuit applications such as in mobile and Internet communications devices and automotive radar systems.

The high melt temperature of ULTRALAM 3850HT LCP circuit materials helps these materials survive multiple solder reflow procedures and increases the multilayer board (MLB) processing temperature window. The LCP circuit materials feature a design dielectric constant of 3.14 at 10 GHz and +23°C. The dissipation factor is typically 0.0020 at 10 GHz and +23°C. The coefficient of thermal expansion (CTE) (from +30 to +150°C) is typically 18 ppm/°C in the x and y dimensions of the material and 200 ppm/°C through the thickness (z dimension) of the material providing good dimensional stability, predictable MLB scaling, and good MLB registration. The circuit material features thermal conductivity of 0.2 W/m/°K and thermal coefficient of dielectric constant of +24 ppm/°C from -50°C to +150°C.

Rogers ULTRALAM 3850HT circuit materials are available in panels of double copper-clad laminates and can be used with Rogers ULTRALAM 3908 bonding film for multilayer constructions. Standard panel sizes include 18 x 12 in. (457 x 305 mm) and 18 x 24 in. (457 x 610 mm) with ¼-oz. (9-µm) and ½-oz. (18-µm) low-profile electrodeposited (ED) copper. Panels with rolled copper and in custom sizes are available upon request.

About Rogers Corporation

Rogers Corporation (NYSE:ROG) is a global leader in engineered materials to power, protect, and connect our world. With more than 180 years of materials science experience, Rogers delivers high-performance solutions that enable clean energy, internet connectivity, advanced transportation and other technologies where reliability is critical. Rogers delivers Power Electronics Solutions for energy-efficient motor drives, vehicle electrification and alternative energy; High Performance Foams for sealing, vibration management and impact protection in mobile devices, transportation interiors, industrial equipment and performance apparel; and Printed Circuit Materials for wireless infrastructure, automotive safety and radar systems. Headquartered in Connecticut (USA), Rogers operates manufacturing facilities in the United States, China, Germany, Belgium, Hungary, and South Korea, with joint ventures and sales offices worldwide. For more information, visit www.rogerscorp.com.